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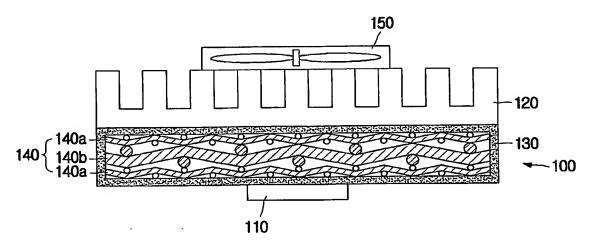
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(54) Title: FLAT PLATE HEAT TRANSFER DEVICE



(57) Abstract: Disclosed is a flat plate heat transfer device, which includes a thermally conductive flat case installed between a heat source and a heat emitting unit and containing a working fluid evaporated with absorbing heat from the heat source and condensed with emitting heat to the heat emitting unit; and a mesh layer aggregate installed in the flat case and having a structure that a fine mesh layer for providing a flowing path of liquid and a coarse mesh layer for providing a flowing path of liquid and a dispersion path of vapor simultaneously are laminated. On occasions, the coarse and the fine mesh layers are alternately laminated repeatedly, and the fine mesh layer is replaced with a wick structure. The coarse mesh layer is preferably a screen mesh layer with wire diameter of 0.2 mm ~ 0.4 mm and mesh number of 10 ~ 20. This device improves heat transfer performance.



For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.